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(54) **POWER AND TEMPERATURE
MANAGEMENT FOR FUNCTIONAL
BLOCKS IMPLEMENTED BY A 3D
STACKED INTEGRATED CIRCUIT**

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(57)

ABSTRACT

A three-dimensional stacked integrated circuit (3D SIC) having a non-volatile memory die, a volatile memory die, a logic die, and a thermal management component. The non-volatile memory die, the volatile memory die, the logic die, and the thermal management component are stacked. The thermal management component can be stacked in between the non-volatile memory die and the logic die, stacked in between the volatile memory die and the logic die, or both.

